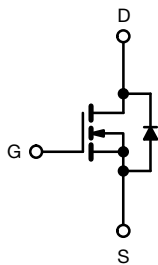
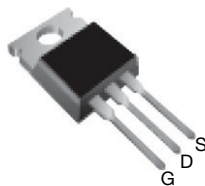


Power MOSFET

TO-220AB


N-Channel MOSFET

FEATURES

- Low gate charge Q_g results in simple drive Requirement
- Improved gate, avalanche, and dynamic dV/dt ruggedness
- Fully characterized capacitance and avalanche voltage and current
- Low t_{rr} and soft diode recovery
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS*
Available

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

APPLICATIONS

- Switch mode power supply (SMPS)
- Uninterruptible power supply
- High speed power switching
- ZVS and high frequency circuit
- PWM inverters

PRODUCT SUMMARY

V_{DS} (V)	500	
$R_{DS(on)}$ (Ω)	$V_{GS} = 10\text{ V}$	0.28
Q_g max. (nC)	130	
Q_{gs} (nC)	33	
Q_{gd} (nC)	59	
Configuration	Single	

ORDERING INFORMATION

Package	TO-220AB
Lead (Pb)-free	IRFB17N50LPbF

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-source voltage	V_{DS}	500	V
Gate-source voltage	V_{GS}	± 30	
Continuous drain current	$V_{GS} \text{ at } 10\text{ V}$	$T_C = 25^\circ\text{C}$	A
		$T_C = 100^\circ\text{C}$	
Pulsed drain current ^a	I_{DM}	64	
Linear derating factor		1.8	W/ $^\circ\text{C}$
Single pulse avalanche energy ^b	E_{AS}	390	mJ
Repetitive avalanche current ^a	I_{AR}	16	A
Repetitive avalanche energy ^a	E_{AR}	22	mJ
Maximum power dissipation	$T_C = 25^\circ\text{C}$	P_D	220
Peak diode recovery dV/dt ^c	dV/dt	13	V/ns
Operating junction and storage temperature range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$
Soldering recommendations (peak temperature) ^d	For 10 s	300	
Mounting torque	6-32 or M3 screw	10	lbf · in
		1.1	N · m

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- Starting $T_J = 25^\circ\text{C}$, $L = 3.0\text{ mH}$, $R_g = 25\ \Omega$, $I_{AS} = 16\text{ A}$ (see fig. 12)
- $I_{SD} \leq 16\text{ A}$, $dI/dt \leq 347\text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DS}$, $T_J \leq 150^\circ\text{C}$
- 1.6 mm from case

**THERMAL RESISTANCE RATINGS**

PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R_{thJA}	-	62	°C/W
Case-to-sink, flat, greased surface	R_{thCS}	0.50	-	
Maximum junction-to-case (drain)	R_{thJC}	-	0.56	

SPECIFICATIONS ($T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

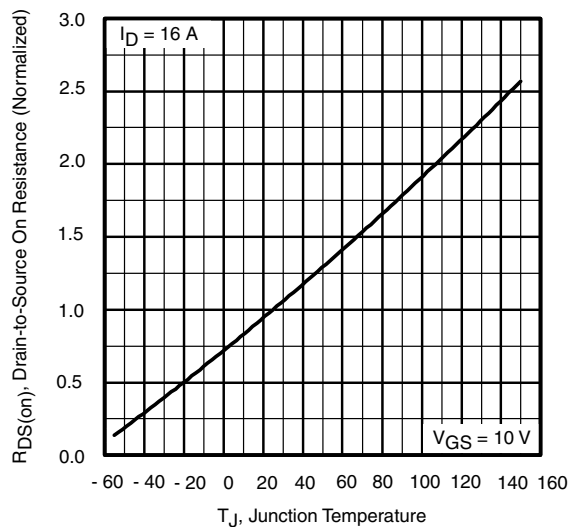
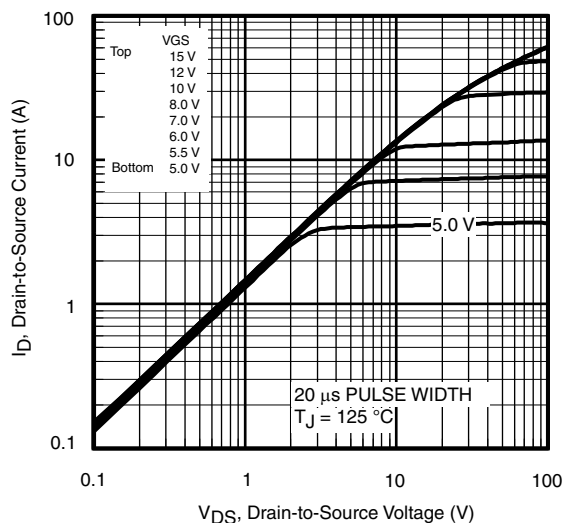
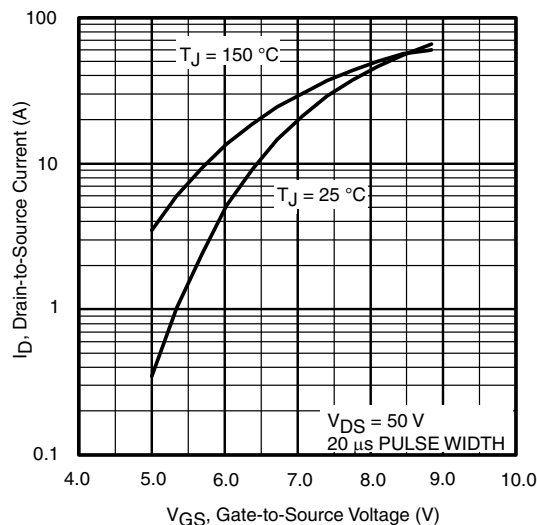
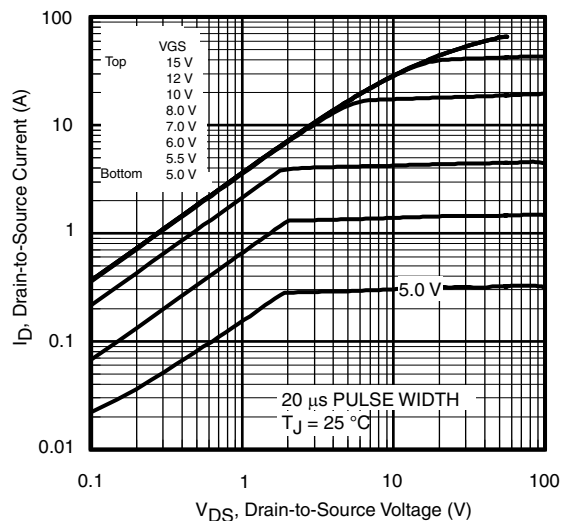
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0\text{ V}$, $I_D = 250\text{ }\mu\text{A}$	500	-	-	V
V_{DS} temperature coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^{\circ}\text{C}$, $I_D = 1\text{ mA}$	-	0.6	-	V/°C
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$	3.0	-	5.0	V
Gate-source leakage	I_{GSS}	$V_{GS} = \pm 30\text{ V}$	-	-	± 100	nA
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 500\text{ V}$, $V_{GS} = 0\text{ V}$	-	-	50	μA
		$V_{DS} = 400\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	-	2.0	mA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$, $I_D = 9.9\text{ A}^b$	-	0.28	0.32	Ω
Forward transconductance	g_{fs}	$V_{DS} = 50\text{ V}$, $I_D = 9.9\text{ A}^b$	11	-	-	S
Dynamic						
Input capacitance	C_{iss}	$V_{GS} = 0\text{ V}$, $V_{DS} = 25\text{ V}$, $f = 1.0\text{ MHz}$, see fig. 5	-	2760	-	pF
Output capacitance	C_{oss}		-	325	-	
Reverse transfer capacitance	C_{rss}		-	37	-	
Output capacitance	C_{oss}	$V_{GS} = 0\text{ V}$, $V_{DS} = 1.0\text{ V}$, $f = 1.0\text{ MHz}$	-	3690	-	pF
		$V_{GS} = 0\text{ V}$, $V_{DS} = 400\text{ V}$, $f = 1.0\text{ MHz}$	-	84	-	
Effective output capacitance	$C_{oss\text{ eff.}}$	$V_{GS} = 0\text{ V}$, $V_{DS} = 0\text{ V to } 400\text{ V}^c$	-	159	-	
Total gate charge	Q_g	$V_{GS} = 10\text{ V}$, $I_D = 16\text{ A}$, $V_{DS} = 400\text{ V}$, see fig. 6 and 13 ^b	-	-	130	nC
Gate-source charge	Q_{gs}		-	-	33	
Gate-drain charge	Q_{gd}		-	-	59	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 250\text{ V}$, $I_D = 16\text{ A}$, $R_g = 7.5\text{ }\Omega$, see fig. 10 ^b	-	21	-	ns
Rise time	t_r		-	51	-	
Turn-off delay time	$t_{d(off)}$		-	50	-	
Fall time	t_f		-	28	-	
Gate input resistance	R_g	$f = 1\text{ MHz}$, open drain	0.3	-	1.4	Ω
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	16	A
Pulsed diode forward current ^a	I_{SM}		-	-	64	
Body diode voltage	V_{SD}	$T_J = 25\text{ }^{\circ}\text{C}$, $I_S = 16\text{ A}$, $V_{GS} = 0\text{ V}^b$	-	-	1.5	V
Body diode reverse recovery time	t_{rr}	$T_J = 25\text{ }^{\circ}\text{C}$	-	170	250	ns
		$T_J = 125\text{ }^{\circ}\text{C}$	-	220	330	
Body diode reverse recovery charge	Q_{rr}	$T_J = 25\text{ }^{\circ}\text{C}$	-	470	710	nC
		$T_J = 125\text{ }^{\circ}\text{C}$	-	810	1210	
Reverse recovery current	I_{RRM}		-	7.3	11	A
Forward turn-on time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)				

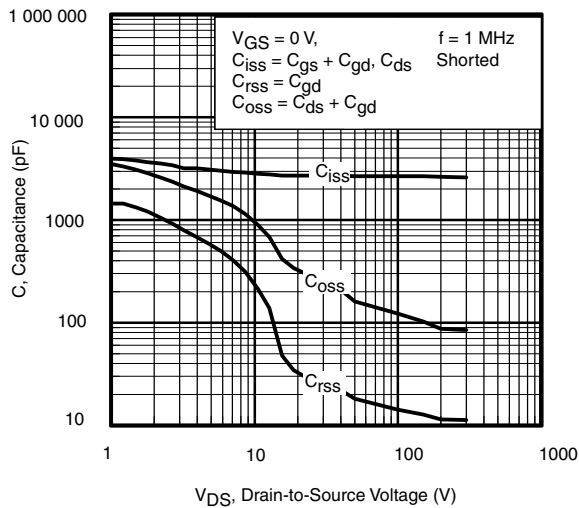
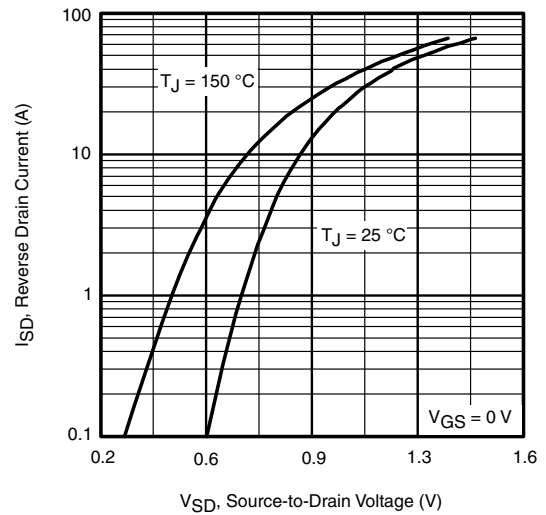
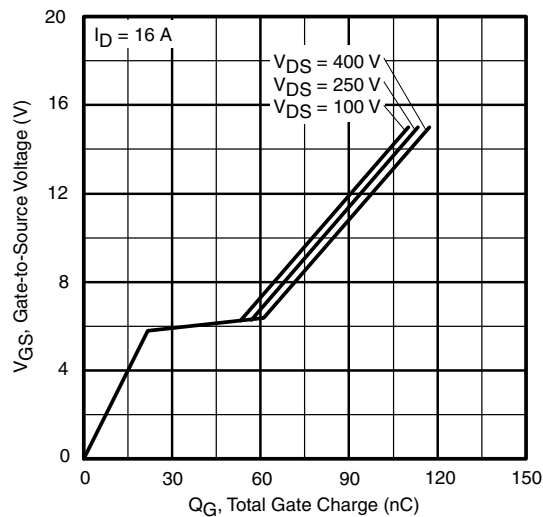
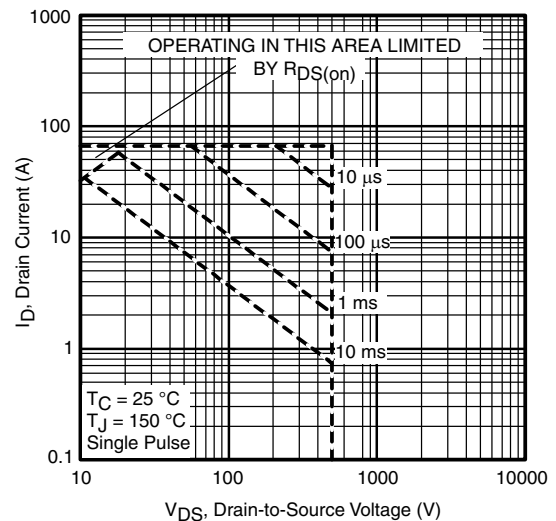
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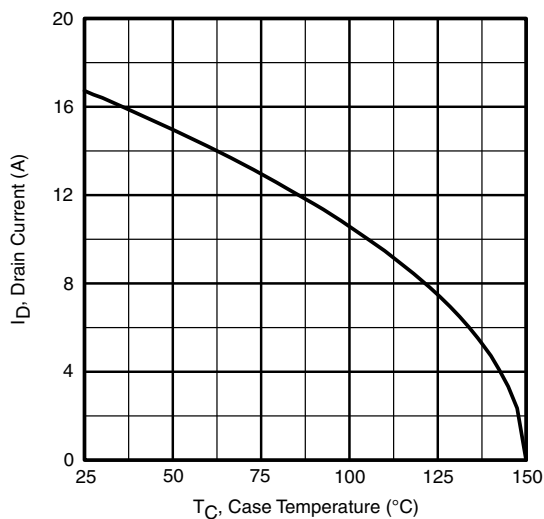
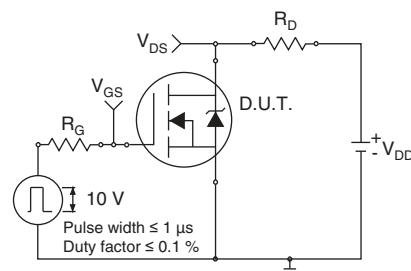
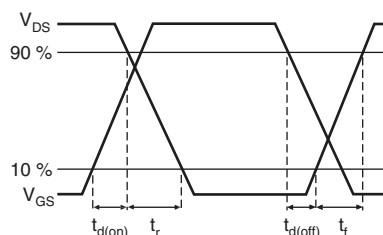
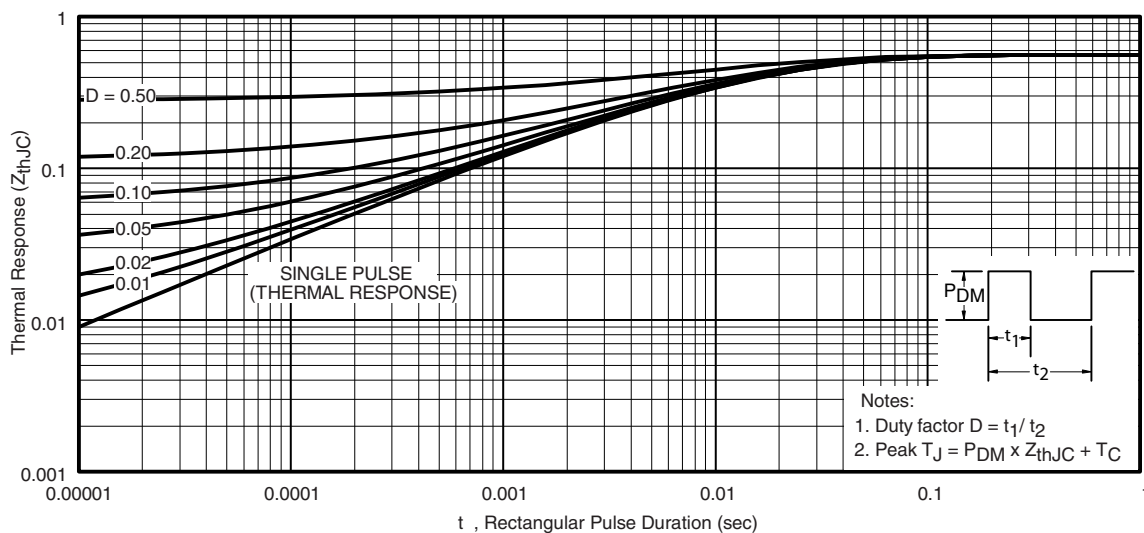
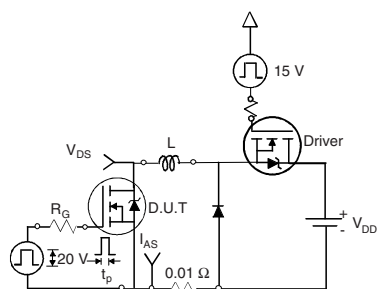
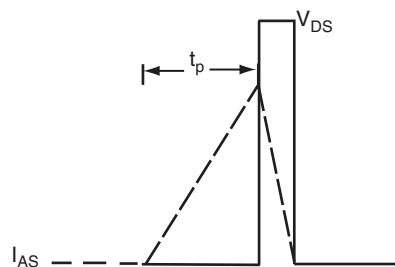
- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)




Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

Fig. 7 - Typical Source-Drain Diode Forward Voltage

Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

Fig. 8 - Maximum Safe Operating Area


Fig. 9 - Maximum Drain Current vs. Case Temperature

Fig. 10a - Switching Time Test Circuit

Fig. 10b - Switching Time Waveforms

Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

Fig. 12a - Unclamped Inductive Test Circuit

Fig. 12b - Unclamped Inductive Waveforms

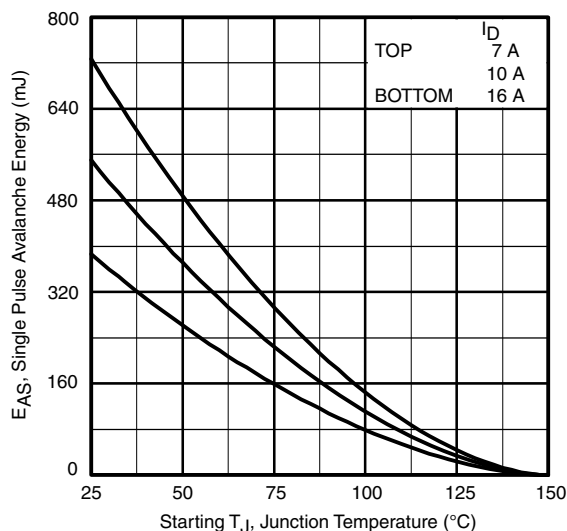


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

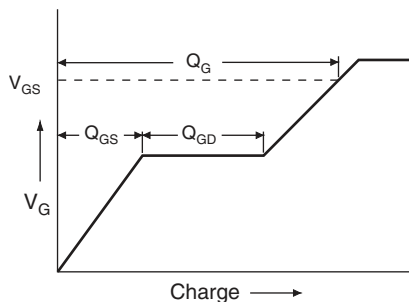


Fig. 13a - Basic Gate Charge Waveform

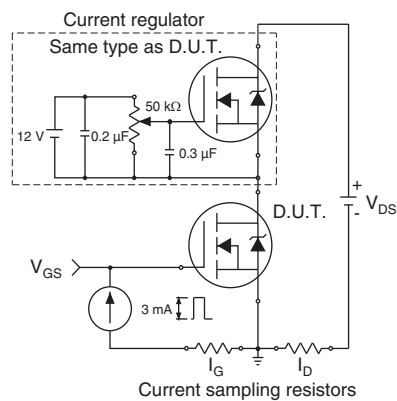
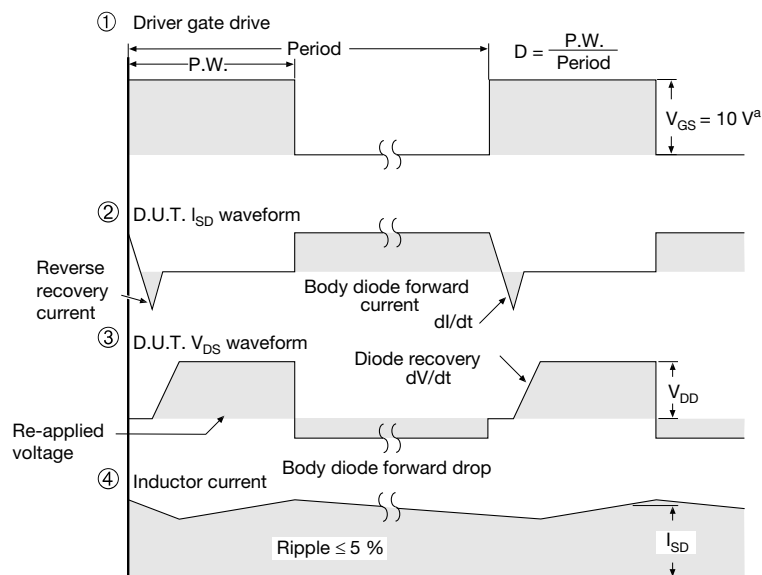
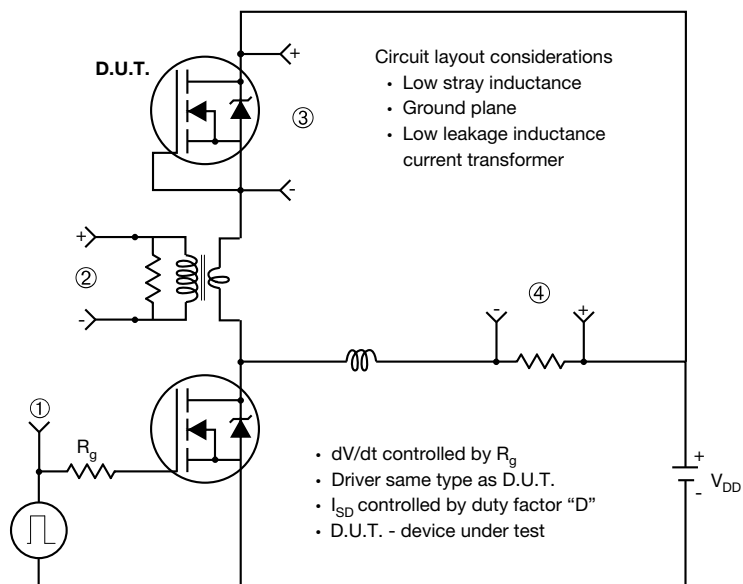


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



Note

a. $V_{GS} = 5\text{ V}$ for logic level devices

Fig. 14 - For N-Channel

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